

Serial No. 10/605,041

Attachment A

Replacement paragraph with markings to show the changes made.

Turning now to Figs. 9 and 10, two examples of suitable low aspect ratio filler configurations are shown which are employed in the composition of Fig. 4. Fig. 9 shows a substantially spheroid filler configuration 130 where the diameter of the member is D. As a result, the aspect of this filler configuration is approximately 1:1. In addition, Fig. 10 illustrates a grain-like or granular filler configuration 132 to serve as the low aspect ratio filler 114. This granular configuration 132 is somewhat random in shape and may have height H height L to width W ratio of 2:1, or the like. The low aspect ratio filler 114, in accordance with the present invention, is of a ratio of 5:1 or less. Further, the material employed for the low aspect ratio filler 114 may be aluminum, alumina, copper, magnesium, brass and carbon. The low aspect ratio filler is preferably approximately 10/1000 of an inch in diameter or along its width but may be of different sizes depending on the application at hand. As with the high aspect ratio filler, the low aspect ratio filler may be selected to enhance thermal or electrical conductivity. Further, the low aspect ratio may be selected that has both thermal and electrical properties depending on the application.